TXU0101 具有施密特触发输入和三态输出的 一位定向电压电平转换器

1 特性

- 完全可配置的双电源轨设计允许各个端口在 1.1V 至 5.5V 范围内运行
- 在 3.3V 至 5.0V 范围内，支持最高 200Mbps 的速率
- 施密特触发输入可实现慢速和高噪声输入
- 带集成静态下拉电阻器的输入阻止通道流动
- 高驱动强度（在 5V 时最高 12mA）
- 低功耗
  - 最大值 xμA (25°C)
  - 最大值 xμA（-40°C 至 125°C）
- V_{CC} 隔离和 V_{CC} 断开 ($I_{off-float}$) 特性
  - 如果任何一个 V_{CC} 输入低于 100mV 或已断开，则所有输出均禁用且处于高阻抗状态
- I_{off} 支持局部断电模式运行
- 带有 $V_{CC(MIN)}$ 电路的控制逻辑 (OE) 允许从端口 A 或 B 进行控制
- 引脚排列兼容 TXB 系列电平转换器
- 工作温度范围为 –40°C 至 +125°C
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范
- ESD 保护性能超过 JESD 22 规范要求
  - 2500V 人体放电模型
  - 1500V 充电器件模型

2 应用

- 消除缓慢或嘈杂输入信号
- 驱动指示 LED 或蜂鸣器
- 机械开关去抖
- 通用 I/O 电平转换
- 推挽电平转换（UART、SPI、JTAG 等等）

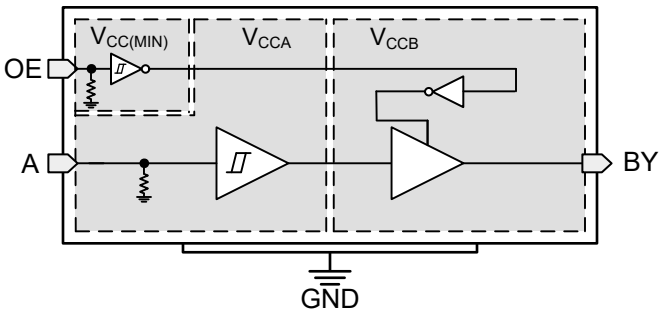
3 说明

TXU0101 是一款 1 位双电源同相定向电压电平转换器件。A 引脚以 V_{CCA} 逻辑电平为基准，OE 引脚可以 V_{CCA} 或 V_{CCB} 逻辑电平为基准，B 引脚以 V_{CCB} 逻辑电平为基准。A 端口能够接受 1.1V 至 5.5V 的输入电压，而 B 端口也可接受 1.1V 至 5.5V 的输入电压。如果 OE 相对于任一电源设为高电平，可能会发生从 A 到 B 的定向数据传输。OE 设为低电平时，所有输出引脚均处于高阻抗状态。请参阅*器件功能模式*，简要了解控制逻辑运行。

器件信息(1)

器件型号	封装	封装尺寸（标称值）
TXU0101	SOT-23 (DBV) (6)	2.90mm × 1.60mm
	SC70 (DCK) (6)	2.00mm × 1.25mm
	SOT-5X3 (DRL) (6)	1.60mm × 1.20mm
	SON (DRY) (6)	1.45mm × 1.00mm
	X2SON (DTQ) (6)	1.00mm × 0.80mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



TXU0101 功能方框图

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4 Revision History

DATE	REVISION	NOTES
February 2022	*	Initial Release

5 Pin Configuration and Functions—TXU0101

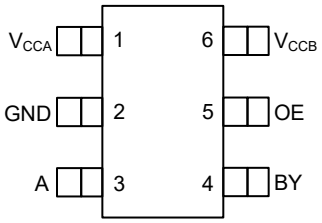


图 5-1. DBV Package 6-Pin SOT-23 Transparent Top View

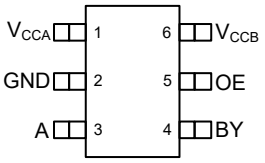


图 5-2. DCK Package 6-Pin SC70 Transparent Top View

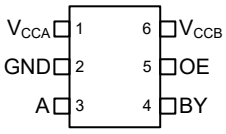


图 5-3. DRL Package 6-Pin SOT-5X3 Transparent Top View

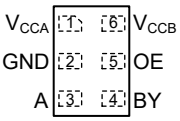


图 5-4. DRY Package 6-Pin SON Transparent Top View

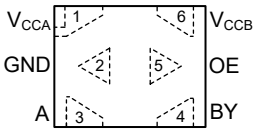


图 5-5. DTQ Package 6-Pin X2SON Transparent Top View

表 5-1. TXU0101 Pin Functions

PIN		TYPE(1)	DESCRIPTION
NAME	NO.		
V_{CCA}	1	—	A-port supply voltage. 1.1 V ⩽ V_{CCA} ⩽ 5.5 V
GND	2	—	Ground
A	3	I	Input A. Referenced to V_{CCA}.
BY	4	O	Output B. Referenced to V_{CCB}.
OE	5	I	Output Enable. Pull to GND to place all outputs in high-impedance mode. Pull to V_{CCA} or V_{CCB} to enable all outputs.
V_{CCB}	6	—	B-port supply voltage. 1.1 V ⩽ V_{CCB} ⩽ 5.5 V

(1) I = input, O = output.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CCA}	Supply voltage A		– 0.5	6.5	V
V_{CCB}	Supply voltage B		– 0.5	6.5	V
V_I	Input Voltage(2)	I/O Ports (A Port)	– 0.5	6.5	V
		I/O Ports (B Port)	– 0.5	6.5	
		OE	– 0.5	6.5	
V_O	Voltage applied to any output in the high-impedance or power-off state(2)	A Port	– 0.5	6.5	V
		B Port	– 0.5	6.5	
V_O	Voltage applied to any output in the high or low state(2) (3)	A Port	– 0.5	V_{CCA} + 0.5	V
		B Port	– 0.5	V_{CCB} + 0.5	
I_{IK}	Input clamp current	V_I < 0	– 20		mA
I_{OK}	Output clamp current	V_O < 0	– 20		mA
I_O	Continuous output current		– 25	25	mA
	Continuous current through V_{CC} or GND		– 100	100	mA
T_j	Junction Temperature			150	°C
T_{stg}	Storage temperature		– 65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions.* If briefly ooperating outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, this device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The output positive-voltage rating may be exceeded up to 6.5 V maximum if the output current rating is observed.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2500	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002 (2)	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted) (1) (2) (3)

			MIN	MAX	UNIT
V_{CCA}	Supply voltage A		1.08	5.5	V
V_{CCB}	Supply voltage B		1.08	5.5	V
I_{OH}	High-level output current	V_{CCO} = 1.1 V		–1.5	mA
		V_{CCO} = 1.4 V		–3	
		V_{CCO} = 1.65 V		–4.5	
		V_{CCO} = 2.3 V		–8	
		V_{CCO} = 3 V		–10	
		V_{CCO} = 4.5 V		–12	
I_{OL}	Low-level output current	V_{CCO} = 1.1 V		1.5	mA
		V_{CCO} = 1.4 V		3	
		V_{CCO} = 1.65 V		4.5	
		V_{CCO} = 2.3 V		8	
		V_{CCO} = 3 V		10	
		V_{CCO} = 4.5 V		12	
V_I	Input voltage (3)		0	5.5	V
V_O	Output voltage	Active State	0	V_{CCO}	V
		Tri-State	0	5.5	
T_A	Operating free-air temperature		–40	125	°C

(1) V_{CCI} is the V_{CC} associated with the input port.
(2) V_{CCO} is the V_{CC} associated with the output port.
(3) All control inputs and data I/Os of this device have weak pulldowns to ensure the line is not floating when undefined external to the device. The input leakage from these weak pulldowns is defined by the I_I specification indicated under Electrical Characteristics.

6.4 Thermal Information

THERMAL METRIC(1)		TXU0101					UNIT
		DBV (SOT-23)	DCK (SC70)	DRL (SOT-5X3)	DRY (SON)	DTQ (X2SON)	
		8 PINS	8 PINS	8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	TBD	215.9	TBD	279.2	267.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	TBD	143.2	TBD	172.6	128.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	TBD	76.6	TBD	154.6	188.9	°C/W
Y_{JT}	Junction-to-top characterization parameter	TBD	58.6	TBD	22.1	4.5	°C/W
Y_{JB}	Junction-to-board characterization parameter	TBD	76.2	TBD	153.8	188.4	°C/W
$R_{\theta JC(bottom)}$	Junction-to-case (bottom) thermal resistance	TBD	N/A	TBD	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)(1) (2)

PARAMETER		TEST CONDITIONS	V_{CCA}	V_{CCB}	Operating free-air temperature (T_A)									UNIT
					25°C			– 40°C to 85°C			– 40°C to 125°C			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{T+}	Positive-going input-threshold voltage	Data Inputs (Ax, Bx) (Referenced to V_{CCI})	1.1 V	1.1 V				0.44		0.88	0.44		0.88	V
			1.4 V	1.4 V				0.60		0.98	0.60		0.98	
			1.65 V	1.65 V				0.76		1.13	0.76		1.13	
			2.3 V	2.3 V				1.08		1.56	1.08		1.56	
			3 V	3 V				1.48		1.92	1.48		1.92	
			4.5 V	4.5 V				2.19		2.74	2.19		2.74	
			5.5 V	5.5 V				2.65		3.33	2.65		3.33	
		OE (Referenced to V_{CCA} or V_{CCB})	1.1 V	1.1 V				0.44		0.88	0.44		0.88	V
			1.4 V	1.4 V				0.60		0.98	0.60		0.98	
			1.65 V	1.65 V				0.76		1.13	0.76		1.13	
			2.3 V	2.3 V				1.08		1.56	1.08		1.56	
			3 V	3 V				1.48		1.92	1.48		1.92	
			4.5 V	4.5 V				2.19		2.74	2.19		2.74	
			5.5 V	5.5 V				2.65		3.33	2.65		3.33	
V_{T-}	Negative-going input-threshold voltage	Data Inputs (Ax, Bx) (Referenced to V_{CCI})	1.1 V	1.1 V				0.17		0.48	0.17		0.48	V
			1.4 V	1.4 V				0.28		0.59	0.28		0.59	
			1.65 V	1.65 V				0.35		0.69	0.35		0.69	
			2.3 V	2.3 V				0.56		0.97	0.56		0.97	
			3 V	3 V				0.89		1.5	0.89		1.5	
			4.5 V	4.5 V				1.51		1.97	1.51		1.97	
			5.5 V	5.5 V				1.88		2.4	1.88		2.4	
		OE (Referenced to V_{CCA} or V_{CCB})	1.1 V	1.1 V				0.17		0.48	0.17		0.48	V
			1.4 V	1.4 V				0.28		0.59	0.28		0.59	
			1.65 V	1.65 V				0.35		0.69	0.35		0.69	
			2.3 V	2.3 V				0.56		0.97	0.56		0.97	
			3 V	3 V				0.89		1.5	0.89		1.5	
			4.5 V	4.5 V				1.51		1.97	1.51		1.97	
			5.5 V	5.5 V				1.88		2.46	1.88		2.46	
ΔV_T	Input-threshold hysteresis (V_{T+} – V_{T-})	Data Inputs (Ax, Bx) (Referenced to V_{CCI})	1.1 V	1.1 V				0.2		0.4	0.2		0.4	V
			1.4 V	1.4 V				0.25		0.5	0.25		0.5	
			1.65 V	1.65 V				0.3		0.55	0.3		0.55	
			2.3 V	2.3 V				0.38		0.65	0.38		0.65	
			3 V	3 V				0.46		0.72	0.46		0.72	
			4.5 V	4.5 V				0.58		0.93	0.58		0.93	
			5.5 V	5.5 V				0.69		1.06	0.69		1.06	
		OE (Referenced to V_{CCA} or V_{CCB})	1.1 V	1.1 V				0.15		0.41	0.15		0.41	V
			1.4 V	1.4 V				0.2		0.5	0.2		0.5	
			1.65 V	1.65 V				0.23		0.55	0.23		0.55	
			2.3 V	2.3 V				0.32		0.65	0.32		0.65	
			3 V	3 V				0.39		0.72	0.39		0.72	
			4.5 V	4.5 V				0.57		0.97	0.57		0.97	
			5.5 V	5.5 V				0.69		1.18	0.69		1.18	

6.5 Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)(1) (2)

PARAMETER		TEST CONDITIONS	V_{CCA}	V_{CCB}	Operating free-air temperature (T_A)									UNIT
					25°C			– 40°C to 85°C			– 40°C to 125°C			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{OH}	High-level output voltage (3)	I_{OH} = – 0.1 mA	1.1V – 5.5V	1.1V – 5.5V				V_{CCO} – 0.1			V_{CCO} – 0.1			V
		I_{OH} = – 0.5 mA	1.1 V	1.1 V				0.82			0.82			
		I_{OH} = – 3 mA	1.4 V	1.4 V				1			1			
		I_{OH} = – 4.5 mA	1.65 V	1.65 V				1.2			1.2			
		I_{OH} = – 8 mA	2.3 V	2.3 V				1.7			1.7			
		I_{OH} = – 10 mA	3 V	3 V				2.2			2.2			
		I_{OH} = – 12 mA	4.5 V	4.5 V				3.7			3.7			
V_{OL}	Low-level output voltage (4)	I_{OL} = 0.1 mA	1.1V – 5.5V	1.1V – 5.5V						0.1			0.1	V
		I_{OL} = 0.5 mA	1.1 V	1.1 V						0.27			0.27	
		I_{OL} = 3 mA	1.4 V	1.4 V						0.35			0.35	
		I_{OL} = 4.5 mA	1.65 V	1.65 V						0.45			0.45	
		I_{OL} = 8 mA	2.3 V	2.3 V						0.7			0.7	
		I_{OL} = 10 mA	3 V	3 V						0.8			0.8	
		I_{OL} = 8 mA	4.5 V	4.5 V						0.55			0.55	
		I_{OL} = 12 mA	4.5 V	4.5 V						0.8			0.8	
I_I	Input leakage current	OE V_I = V_{CC} or GND	1.1V – 5.5V	1.1V – 5.5V	-0.1		1.5	-0.1		1.5	-0.1		2	µA
		Data Inputs (Ax, Bx) V_I = V_{CCI} or GND	1.1V – 5.5V	1.1V – 5.5V	– 0.1		1.5	– 0.1		1.5	– 2		2	µA
I_{off}	Partial power down current	A Port or B Port V_I or V_O = 0 V - 5.5 V	0 V	0 V - 5.5 V	– 1.5		1.5	– 2		2	– 2.5		2.5	µA
			0 V - 5.5 V	0 V	– 1.5		1.5	– 2		2	– 2.5		2.5	
$I_{off-float}$	Floating supply Partial power down current	A Port or B Port V_I or V_O = GND	Floating(5)	0 V - 5.5 V	– 1.5		1.5	– 2		2	– 2.5		2.5	µA
			0 V - 5.5 V	Floating(5)	– 1.5		1.5	– 2		2	– 2.5		2.5	
I_{OZ}	Tri-state output current	A or B Port: V_I = V_{CCI} or GND V_O = V_{CCO} or GND OE = GND	1.1V – 5.5V	1.1V – 5.5V	– 0.3		0.3	– 1		1	– 2		2	µA
I_{CCA}	V_{CCA} supply current	V_I = V_{CCI} or GND I_O = 0	1.1V – 5.5V	1.1V – 5.5V			1.5			2.5			6	µA
			0 V	5.5 V	– 0.3			– 1			– 1			
			5.5 V	0 V			1			1.5			3	
		V_I = GND I_O = 0	5.5 V	Floating(5)			1.5			7			15	
I_{CCB}	V_{CCB} supply current	V_I = V_{CCI} or GND I_O = 0	1.1V – 5.5V	1.1V – 5.5V			1.5			2.5			6	µA
			0 V	5.5 V			1			1.5			3	
			5.5 V	0 V	– 0.3			– 1			– 1			
		V_I = GND I_O = 0	Floating(5)	5.5 V			1.5			7			15	

6.5 Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)(1) (2)

PARAMETER		TEST CONDITIONS	V_{CCA}	V_{CCB}	Operating free-air temperature (T_A)									UNIT
					25°C			– 40°C to 85°C			– 40°C to 125°C			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
I_{CCA} + I_{CCB}	Combined supply current	V_I = V_{CCI} or GND I_O = 0	1.1V – 5.5V	1.1V – 5.5V			2.5			3			6	µA
C_i	Control Input Capacitance	V_I = 3.3 V or GND	3.3 V	3.3 V		2.75			3			3.5		pF
C_{io}	Data I/O Capacitance	OE = GND, V_O = 1.65V DC +1 MHz -16 dBm sine wave	3.3 V	3.3 V		3			4			4		pF

(1) V_{CCI} is the V_{CC} associated with the input port
(2) V_{CCO} is the V_{CC} associated with the output port
(3) Tested at V_I = $V_{T+(MAX)}$
(4) Tested at V_I = $V_{T-(MIN)}$
(5) Floating is defined as a node that is both not actively driven by an external device and has leakage not exeeding 10nA

6.6 Switching Characteristics, V_{CCA} = 1.2 ± 0.1 V

See 图 7-1 and 表 7-1 for test circuit and loading. See 图 7-2, 图 7-3, and 图 7-4 for measurement waveforms.

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})														UNIT
					1.2 ± 0.1 V			1.5 ± 0.1 V			1.8 ± 0.15 V			2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	Propagation delay	A	B	-40°C to 85°C	3.3		96	0.5		43	0.5		37	0.5		32	0.5		30	0.5		31	ns
				-40°C to 125°C	5.7		60	3.0		39	1.4		33	0.5		28	0.5		27	0.5		26	
		B	A	-40°C to 85°C	3.3		95	1.9		80	0.5		75	0.5		70	0.5		69	0.5		69	
				-40°C to 125°C	5.7		60	4.1		51	2.9		48	1.8		45	1.5		44	1.3		44	
t_{dis}	Disable time	OE	A	-40°C to 85°C	28.8		133	28.5		130	28.4		133	28.8		137	28.4		143	18.7		211	ns
				-40°C to 125°C	43.3		133	43.3		130	43.7		130	44.7		131	45.4		134	31.8		140	
		OE	B	-40°C to 85°C	32.5		150	27.6		117	25.8		110	22.5		104	22.1		112	20.1		181	
				-40°C to 125°C	48.3		149	43.2		120	40.8		113	36.8		104	36.5		107	33.8		111	
t_{en}	Enable time	OE	A	-40°C to 85°C	24.1		237	22.1		229	21.4		230	21.3		232	21.7		235	22.7		244	ns
				-40°C to 125°C	34.9		156	33.3		167	32.0		169	31.7		173	32.0		177	34.2		187	
		OE	B	-40°C to 85°C	21.3		237	14.3		152	11.2		140	8.8		130	8.2		130	8.4		132	
				-40°C to 125°C	29.8		143	23.0		116	18.6		107	15.4		97	14.5		97	14.8		103	

6.7 Switching Characteristics, V_{CCA} = 1.5 ± 0.1 V

See 图 7-1 and 表 7-1 for test circuit and loading. See 图 7-2, 图 7-3, and 图 7-4 for measurement waveforms.

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})																		UNIT
					1.2 ± 0.1 V			1.5 ± 0.1 V			1.8 ± 0.15 V			2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	Propagation delay	A	B	-40°C to 85°C	1.9		80	0.5		31	0.5		25	0.5		19	0.5		17	0.5		15	ns
				-40°C to 125°C	4.1		51	1.6		31	0.5		25	0.5		20	0.5		18	0.5		16	
		B	A	-40°C to 85°C	0.5		43	0.5		31	0.5		28	0.5		26	0.5		25	0.5		24	
				-40°C to 125°C	3.0		39	1.6		31	0.5		28	0.5		26	0.5		25	0.5		24	
t_{dis}	Disable time	OE	A	-40°C to 85°C	20.0		91	19.0		82	18.8		81	19.2		82	19.6		83	12.2		87	ns
				-40°C to 125°C	34.9		95	32.6		86	32.8		85	33.4		87	34.2		88	24.6		92	
		OE	B	-40°C to 85°C	27.4		127	21.7		91	19.9		82	16.3		71	15.9		71	13.7		70	
				-40°C to 125°C	44.4		130	36.7		95	34.7		86	30.2		75	29.8		75	26.6		74	
t_{en}	Enable time	OE	A	-40°C to 85°C	14.9		102	14.4		86	13.5		88	12.7		90	12.6		92	13.2		97	ns
				-40°C to 125°C	25.5		102	25.2		89	24.1		91	22.8		93	22.8		96	23.5		100	
		OE	B	-40°C to 85°C	17.9		175	12.7		80	9.1		69	6.1		57	4.9		53	4.5		54	
				-40°C to 125°C	26.6		135	21.0		81	16.8		71	12.5		60	10.8		56	10.4		57	

6.8 Switching Characteristics, V_{CCA} = 1.8 ± 0.15 V

See 图 7-1 and 表 7-1 for test circuit and loading. See 图 7-2, 图 7-3, and 图 7-4 for measurement waveforms.

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})																	UNIT
					1.2 ± 0.1 V			1.5 ± 0.1 V			1.8 ± 0.15 V			2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	Propagation delay	A	B	-40°C to 85°C	0.5		75	0.5		28	0.5		22	0.5		17	0.5		14	0.5		12	ns
				-40°C to 125°C	2.9		48	0.5		28	0.5		23	0.5		17	0.5		15	0.5		13	
		B	A	-40°C to 85°C	0.5		37	0.5		25	0.5		22	0.5		19	0.5		19	0.5		18	
				-40°C to 125°C	1.4		33	0.5		25	0.5		23	0.5		20	0.5		19	0.5		19	
t_{dis}	Disable time	OE	A	-40°C to 85°C	17.2		79	14.7		67	14.5		65	14.3		65	14.4		66	8.5		68	ns
				-40°C to 125°C	30.9		83	28.0		71	26.6		69	27.5		70	27.2		71	20.0		73	
		OE	B	-40°C to 85°C	25.4		121	18.7		81	16.5		71	12.8		60	12.5		58	9.8		55	
				-40°C to 125°C	41.7		123	34.0		86	30.3		76	26.2		64	25.3		62	21.8		59	
t_{en}	Enable time	OE	A	-40°C to 85°C	10.9		88	9.5		66	9.4		63	8.6		65	8.2		66	8.1		69	ns
				-40°C to 125°C	20.3		87	19.0		69	18.9		67	17.6		68	17.1		70	17.1		73	
		OE	B	-40°C to 85°C	16.7		177	10.4		75	8.1		58	4.9		46	3.3		42	2.2		39	
				-40°C to 125°C	25.1		135	18.7		77	15.5		60	11.0		49	8.7		44	7.3		42	

6.9 Switching Characteristics, V_{CCA} = 2.5 ± 0.2 V

See 图 7-1 and 表 7-1 for test circuit and loading. See 图 7-2, 图 7-3, and 图 7-4 for measurement waveforms.

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})																	UNIT
					1.2 ± 0.1 V			1.5 ± 0.1 V			1.8 ± 0.15 V			2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	Propagation delay	A	B	-40°C to 85°C	0.5		70	0.5		26	0.5		20	0.5		14	0.5		12	0.5		9	ns
				-40°C to 125°C	1.8		45	0.5		26	0.5		20	0.5		14	0.5		12	0.5		10	
		B	A	-40°C to 85°C	0.5		32	0.5		19	0.5		17	0.5		14	0.5		13	0.5		13	
				-40°C to 125°C	0.5		28	0.5		20	0.5		17	0.5		14	0.5		13	0.5		13	
t_{dis}	Disable time	OE	A	-40°C to 85°C	12.9		65	10.5		51	9.0		51	8.1		43	8.4		44	5.0		45	ns
				-40°C to 125°C	24.9		68	21.8		55	19.7		50	18.2		47	18.6		48	15.0		49	
		OE	B	-40°C to 85°C	23.2		112	16.5		74	14.0		61	9.0		46	9.1		44	6.4		39	
				-40°C to 125°C	38.7		115	30.9		79	27.1		66	21.6		51	20.5		48	16.8		43	
t_{en}	Enable time	OE	A	-40°C to 85°C	7.9		80	5.9		50	5.1		44	4.7		39	4.4		40	3.7		41	ns
				-40°C to 125°C	15.6		74	13.5		53	12.4		47	12.0		42	11.5		43	10.8		44	
		OE	B	-40°C to 85°C	16.3		183	9.2		74	6.0		54	4.0		36	2.1		31	0.5		27	
				-40°C to 125°C	24.4		139	17.2		76	13.0		57	9.8		38	7.1		33	4.7		29	

6.10 Switching Characteristics, V_{CCA} = 3.3 ± 0.3 V

See 图 7-1 and 表 7-1 for test circuit and loading. See 图 7-2, 图 7-3, and 图 7-4 for measurement waveforms.

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})														UNIT
					1.2 ± 0.1 V			1.5 ± 0.1 V			1.8 ± 0.15 V			2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	Propagation delay	A	B	-40°C to 85°C	0.5		69	0.5		25	0.5		19	0.5		13	0.5		11	0.5		8	ns
				-40°C to 125°C	1.5		44	0.5		25	0.5		19	0.5		13	0.5		11	0.5		9	
		B	A	-40°C to 85°C	0.5		30	0.5		17	0.5		14	0.5		12	0.5		11	0.5		10	
				-40°C to 125°C	0.5		27	0.5		18	0.5		15	0.5		12	0.5		11	0.5		10	
t_{dis}	Disable time	OE	A	-40°C to 85°C	12.9		62	10.1		47	8.7		42	6.9		39	6.6		39	6.9		40	ns
				-40°C to 125°C	24.0		65	20.6		51	18.4		46	15.7		40	15.3		39	15.9		40	
		OE	B	-40°C to 85°C	22.7		109	15.7		71	13.2		59	8.5		42	7.6		38	4.7		34	
				-40°C to 125°C	37.6		111	29.5		75	25.4		63	19.2		46	18.5		42	14.2		36	
t_{en}	Enable time	OE	A	-40°C to 85°C	6.6		85	4.2		45	3.0		37	2.4		31	2.2		30	1.7		30	ns
				-40°C to 125°C	13.6		72	10.9		47	9.3		40	8.2		33	8.1		32	7.5		33	
		OE	B	-40°C to 85°C	16.3		192	8.9		76	5.4		55	2.6		34	1.8		27	0.5		22	
				-40°C to 125°C	24.3		144	16.7		78	12.2		57	8.0		36	6.6		29	3.7		24	

6.11 Switching Characteristics, V_{CCA} = 5.0 ± 0.5 V

See 图 7-1 and 表 7-1 for test circuit and loading. See 图 7-2, 图 7-3, and 图 7-4 for measurement waveforms.

PARAMETER		FROM	TO	Test Conditions	B-Port Supply Voltage (V_{CCB})														UNIT
					1.2 ± 0.1 V			1.5 ± 0.1 V			1.8 ± 0.15 V			2.5 ± 0.2 V			3.3 ± 0.3 V			5.0 ± 0.5 V			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t_{pd}	Propagation delay	A	B	-40°C to 85°C	0.5		69	0.5		24	0.5		18	0.5		13	0.5		10	0.5		8	ns
				-40°C to 125°C	1.3		44	0.5		24	0.5		19	0.5		13	0.5		11	0.5		8	
		B	A	-40°C to 85°C	0.5		31	0.5		15	0.5		12	0.5		9	0.5		8	0.5		8	
				-40°C to 125°C	0.5		26	0.5		16	0.5		13	0.5		10	0.5		9	0.5		8	
t_{dis}	Disable time	OE	A	-40°C to 85°C	10.8		58	7.7		42	5.9		36	4.2		31	3.4		30	2.8		26	ns
				-40°C to 125°C	20.8		61	17.0		46	14.5		40	11.8		33	10.4		31	9.6		29	
		OE	B	-40°C to 85°C	9.7		109	5.9		69	13.2		56	8.4		40	6.9		36	3.7		29	
				-40°C to 125°C	37.4		111	29.2		73	24.6		60	18.1		43	16.4		39	12.2		31	
t_{en}	Enable time	OE	A	-40°C to 85°C	6.0		102	2.8		44	1.2		33	0.5		25	0.5		22	0.5		21	ns
				-40°C to 125°C	12.4		81	8.8		46	6.5		36	4.7		27	4.2		24	4.4		23	
		OE	B	-40°C to 85°C	16.7		212	8.8		82	4.8		58	1.6		35	0.5		26	0.5		19	
				-40°C to 125°C	24.8		158	16.7		83	11.7		60	6.9		37	4.7		28	3.5		21	

6.12 Operating Characteristics

T_A = 25℃ (1)

PARAMETER		Test Conditions	Supply Voltage (V_{CCB} = V_{CCA})						UNIT
			1.2 ± 0.1V	1.5 ± 0.1V	1.8 ± 0.15V	2.5 ± 0.2V	3.3 ± 0.3V	5.0 ± 0.5V	
			TYP	TYP	TYP	TYP	TYP	TYP	
C_{pdA} (2)	A to B: outputs enabled	A Port CL = 0, RL = Open f = 10 MHz t_{rise} = t_{fall} = 1 ns	2	2	2	2	2	3	pF
	A to B: outputs disabled		2	2	2	2	2	3	
	B to A: outputs enabled		12	12	12	13	13	16	
	B to A: outputs disabled		2	2	2	2	2	3	
C_{pdB} (3)	A to B: outputs enabled	B Port CL = 0, RL = Open f = 10 MHz t_{rise} = t_{fall} = 1 ns	12	12	12	13	13	16	pF
	A to B: outputs disabled		2	2	2	2	2	3	
	B to A: outputs enabled		2	2	2	2	2	3	
	B to A: outputs disabled		2	2	2	2	2	3	

(1) See the *CMOS Power Consumption and C_{pd} Calculation* application report for additional information about how power dissipation capacitance affects power consumption.
(2) A-Port power dissipation capacitance per transceiver.
(3) B-Port power dissipation capacitance per transceiver.

6.13 Typical Characteristics

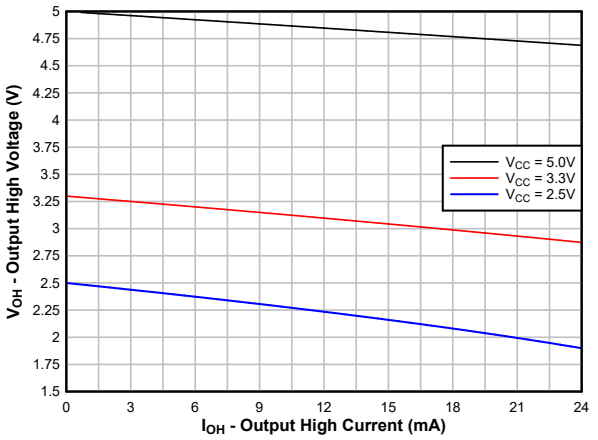


图 6-1. Typical (T_A=25°C) Output High Voltage (V_{OH}) vs Source Current (I_{OH})

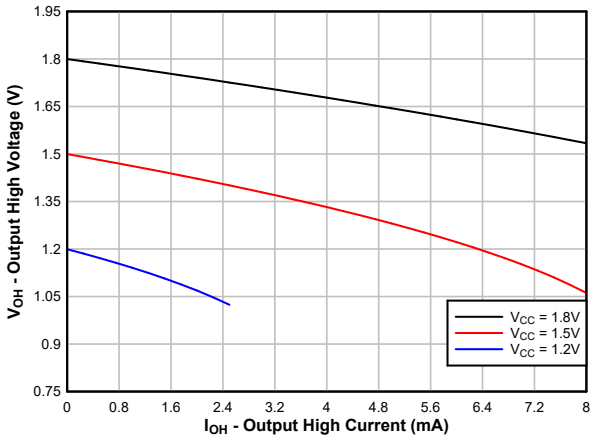


图 6-2. Typical (T_A=25°C) Output High Voltage (V_{OH}) vs Source Current (I_{OH})

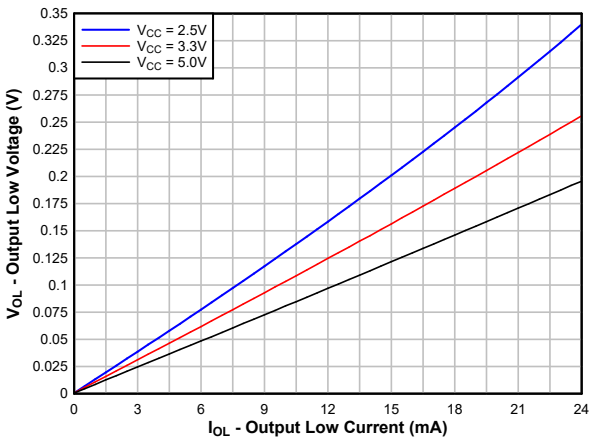


图 6-3. Typical (T_A=25°C) Output Low Voltage (V_{OL}) vs Sink Current (I_{OL})

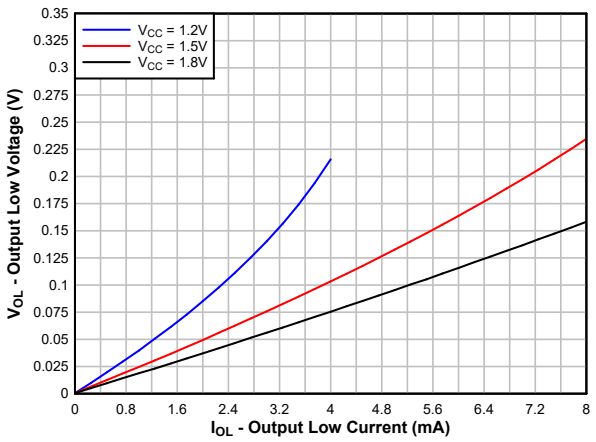


图 6-4. Typical (T_A=25°C) Output Low Voltage (V_{OL}) vs Sink Current (I_{OL})

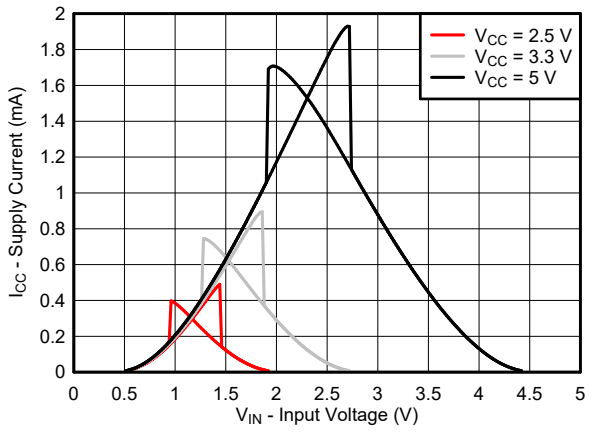


图 6-5. Typical (T_A=25°C) Supply Current (I_{CC}) vs Input Voltage (V_{IN})

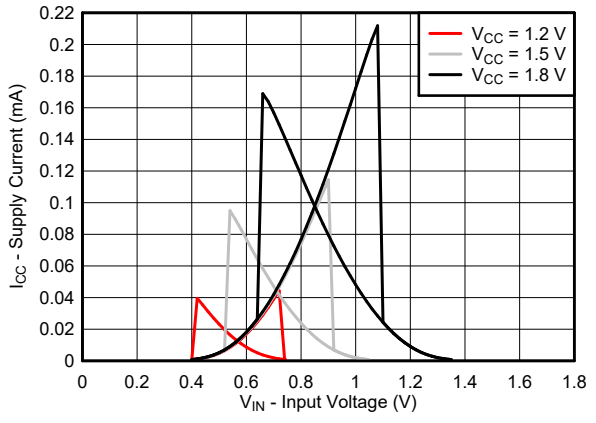


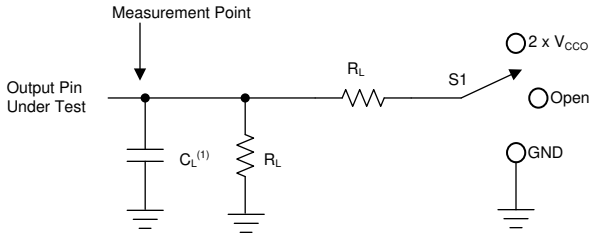
图 6-6. Typical (T_A=25°C) Supply Current (I_{CC}) vs Input Voltage (V_{IN})

7 Parameter Measurement Information

7.1 Load Circuit and Voltage Waveforms

Unless otherwise noted, generators supply all input pulses that have the following characteristics:

- f = 1 MHz
- Z_O = 50 Ω
- $\Delta t/\Delta V \leq$ 1 ns/V

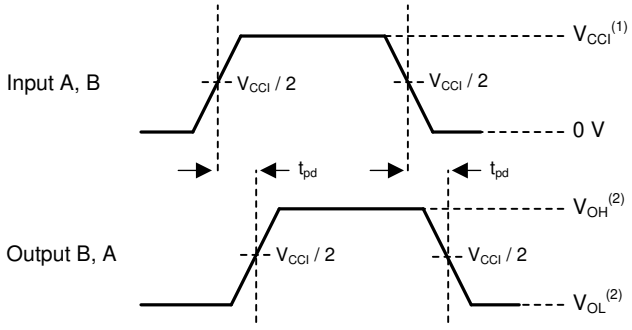


A. C_L includes probe and jig capacitance.

图 7-1. Load Circuit

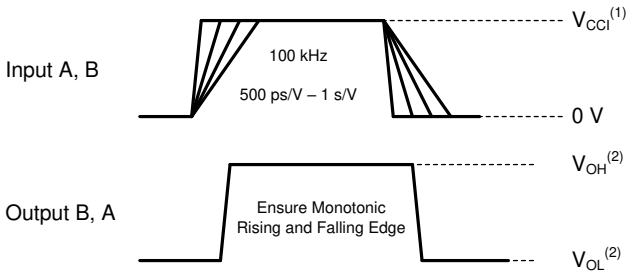
表 7-1. Load Circuit Conditions

Parameter		V_{CCO}	R_L	C_L	S_1	V_{TP}
t_{pd}	Propagation (delay) time	1.1 V – 5.5 V	10 kΩ	5 pF	Open	N/A
t_{en}, t_{dis}	Enable time, disable time	1.1 V – 1.6 V	10 kΩ	5 pF	2 × V_{CCO}	0.1 V
		1.65 V – 2.7 V	10 kΩ	5 pF	2 × V_{CCO}	0.15 V
		3.0 V – 5.5 V	10 kΩ	5 pF	2 × V_{CCO}	0.3 V
t_{en}, t_{dis}	Enable time, disable time	1.1 V – 1.6 V	10 kΩ	5 pF	GND	0.1 V
		1.65 V – 2.7 V	10 kΩ	5 pF	GND	0.15 V
		3.0 V – 5.5 V	10 kΩ	5 pF	GND	0.3 V



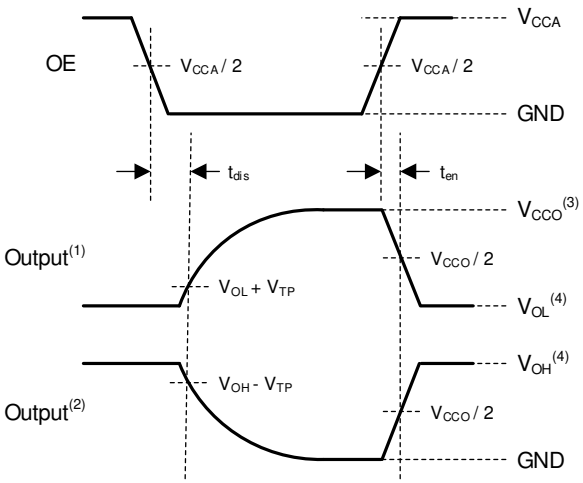
1. V_{CCI} is the supply pin associated with the input port.
2. V_{OH} and V_{OL} are typical output voltage levels that occur with specified R_L, C_L, and S_1

图 7-2. Propagation Delay



1. V_{CCI} is the supply pin associated with the input port.
2. V_{OH} and V_{OL} are typical output voltage levels that occur with specified R_L, C_L, and S_1

图 7-3. Input Transition Rise and Fall Rate



1. Output waveform on the condition that input is driven to a valid Logic Low.
2. Output waveform on the condition that input is driven to a valid Logic High.
3. V_{CCO} is the supply pin associated with the output port.
4. V_{OH} and V_{OL} are typical output voltage levels with specified R_L, C_L, and S_1.

图 7-4. Enable Time And Disable Time

8 Detailed Description

8.1 Overview

The TXU0101 is a 4-bit translating transceiver that uses two individually configurable power-supply rails. The device is operational with V_{CCA} and V_{CCB} supplies as low as 1.1 V and as high as 5.5 V. Additionally, the device can be operated with V_{CCA} = V_{CCB}. The A port is designed to track V_{CCA}, and the B port is designed to track V_{CCB}.

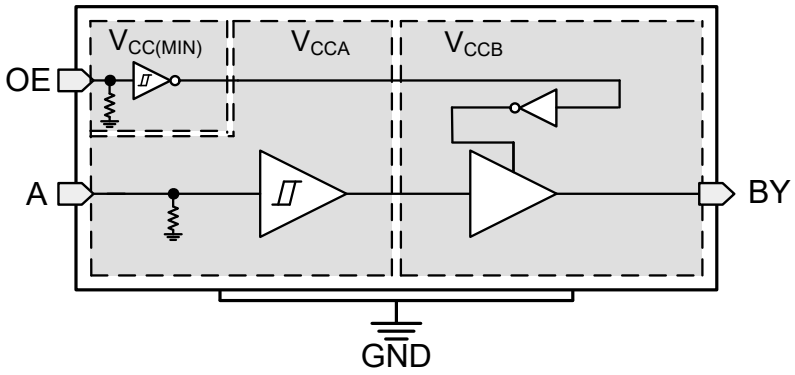
The TXU0101 device is designed for asynchronous communication between data buses, and transmits data with fixed direction from the A bus to the B bus on some channels and from the B bus to the A bus on the remaining channels. The output-enable input (OE) is used to disable the outputs so the buses are effectively isolated. The output-enable pin of the TXU0101 (OE) can be referenced to either V_{CCA} or V_{CCB}. The OE pin can be left floating or externally pulled down to ground to ensure the high-impedance state of the level shifter outputs during power up or power down.

This device is fully specified for partial-power-down applications using the I_{off} current. The I_{off} protection circuitry ensures that no excessive current is drawn from or sourced into an input or output while the device is powered down.

The VCC isolation or VCC disconnect feature ensures that if either VCC is less than 100 mV or disconnected with the complementary supply within recommended operating conditions, outputs are disabled and set to the high-impedance state while the supply current is maintained. The $I_{off-float}$ circuitry ensures that no excessive current is drawn from or sourced into an input or output while the supply is floating.

Glitch-free power supply sequencing allows either supply rail to be powered on or off in any order while providing robust power sequencing performance.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 CMOS Schmitt-Trigger Inputs with Integrated Pulldowns

Standard CMOS inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the *Electrical Characteristics*. The worst case resistance is calculated with the maximum input voltage, given in the *Absolute Maximum Ratings*, and the maximum input leakage current, given in the *Electrical Characteristics*, using ohm's law (R = V ÷ I).

The Schmitt-trigger input architecture provides hysteresis as defined by ΔV_T in the *Electrical Characteristics*, which makes this device extremely tolerant to slow or noisy inputs. Driving the inputs slowly will increase dynamic current consumption of the device. See *Understanding Schmitt Triggers* for additional information regarding Schmitt-trigger inputs.

8.3.1.1 Inputs with Integrated Static Pull-Down Resistors

This device has 5 MΩ typical integrated weak pull-downs for each input. This feature allows all inputs to be left floating without the concern for unstable outputs or increased current consumption. This also helps to reduce external component count for applications where not all channels are used or need to be fixed low. If an external pull-up is required, it should be no larger than 1 MΩ to avoid contention with the 5 MΩ internal pull-down.

8.3.2 Control Logic (OE) with $V_{CC(MIN)}$ Circuitry

The output-enable input (OE) is used to disable the outputs so the buses are effectively isolated. The output-enable pin of the TXU0x04 has $V_{CC(MIN)}$ circuitry, which allows the OE pin to operate with the lower supply voltage. The *Over-Voltage Tolerant Inputs* feature allows the OE pin to operate with the higher supply voltage. This combination means that the enable pin can be referenced to either V_{CCA} or V_{CCB} supply. Multiple permutations of each device are possible since the controller can be placed on either the A or B port and can still control the enable pin.

8.3.3 Balanced High-Drive CMOS Push-Pull Outputs

A balanced output allows the device to sink and source similar currents. The high drive capability of this device creates fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. *Absolute Maximum Ratings* defines the electrical and thermal limits that must be followed at all times.

8.3.4 VCC Isolation and V_{CC} Disconnect

The outputs for this device are disabled and enter a high-impedance state when either supply is <100 mV or left floating (disconnected), with the complementary supply within recommended operating conditions. It is recommended that the inputs are kept low before floating (disconnecting) either supply.

The $I_{CCx(floating)}$ in the *Electrical Characteristics* specifies the maximum supply current. The $I_{off(float)}$ in the *Electrical Characteristics* specifies the maximum leakage into or out of any input or output pin on the device.

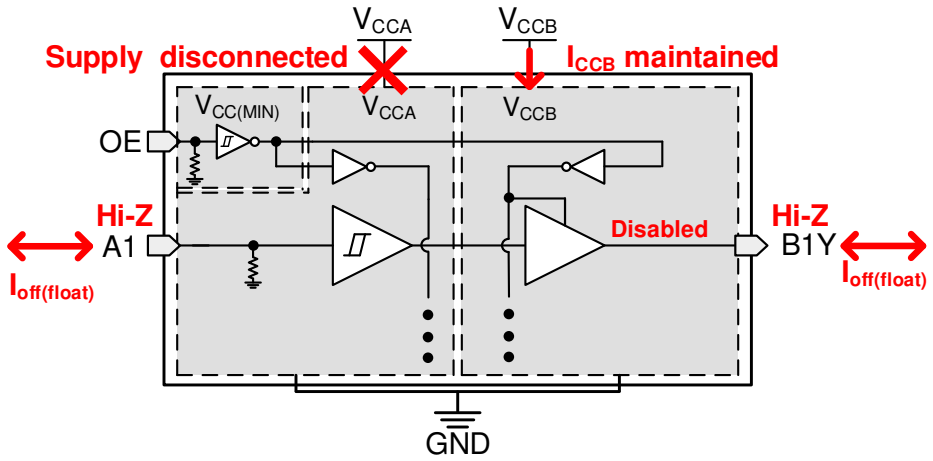


图 8-1. V_{CC} Disconnect Feature

8.3.5 Over-Voltage Tolerant Inputs

Input signals to this device can be driven above the supply voltage so long as they remain below the maximum input voltage value specified in the *Recommended Operating Conditions*.

8.3.6 Glitch-Free Power Supply Sequencing

Either supply rail may be powered on or off in any order without producing a glitch on the inputs or outputs (that is, where the output erroneously transitions to VCC when it should be held low or vice versa). Glitches of this nature can be misinterpreted by a peripheral as a valid data bit, which could trigger a false device reset of the peripheral, a false device configuration of the peripheral, or even a false data initialization by the peripheral.

8.3.7 Negative Clamping Diodes

图 8-2 depicts the inputs and outputs to this device that have negative clamping diodes.

CAUTION

Voltages beyond the values specified in the *Absoulte Maximum Ratings* table can cause damage to the device. The input negative-voltage and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

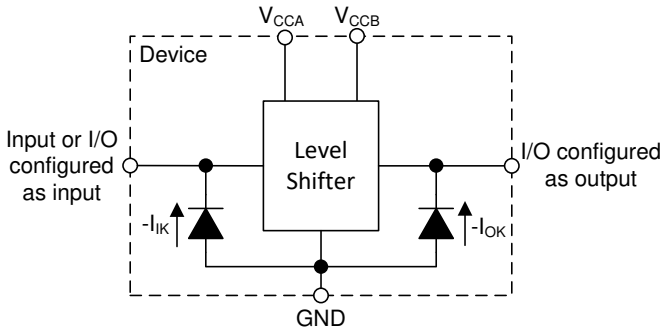


图 8-2. Electrical Placement of Clamping Diodes for Each Input and Output

8.3.8 Fully Configurable Dual-Rail Design

The V_{CCA} and V_{CCB} pins can be supplied at any voltage from 1.1 V to 5.5 V, making the device suitable for translating between any of the voltage nodes (1.2 V, 1.5 V, 1.8 V, 3.3 V, and 5.0 V).

8.3.9 Supports High-Speed Translation

The TXU0101 device can support high data-rate applications. The translated signal data rate can be up to 200 Mbps when the signal is translated from 3.3 V to 5.0 V.

8.4 Device Functional Modes

表 8-1. Function Table

CONTROL INPUTS	Port Status		OPERATION
OE	Input	Output	
H	L	L	Unidirectional non-inverting voltage translation
H	H	H	Unidirectional non-inverting voltage translation
L	X	Hi-Z	Isolation

9 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Application Information

The TXU0101 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The TXU0101 device is ideal for use in applications where a push-pull driver is connected to the data Inputs. The maximum data rate can be up to 200 Mbps when device translates a signal from 3.3 V to 5.0 V.

9.2 Typical Application

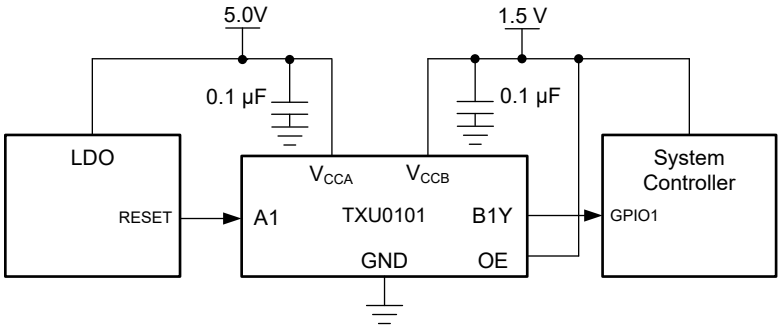


图 9-1. TXU0101 LDO Reset Application

9.2.1 Design Requirements

Use the parameters listed in 表 9-1 for this design example.

表 9-1. Design Parameters

DESIGN PARAMETERS	EXAMPLE VALUES
Input voltage range	1.1 V to 5.5 V
Output voltage range	1.1 V to 5.5 V

9.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
  - Use the supply voltage of the device that is driving the TXU0101 device to determine the input voltage range. For a valid logic-high, the value must exceed the positive-going input-threshold voltage (V_{T+}) of the input port. For a valid logic low the value must be less than the negative-going input-threshold voltage (V_{T-}) of the input port.
- Output voltage range
  - Use the supply voltage of the device that the TXU0101 device is driving to determine the output voltage range.

9.2.3 Application Curve

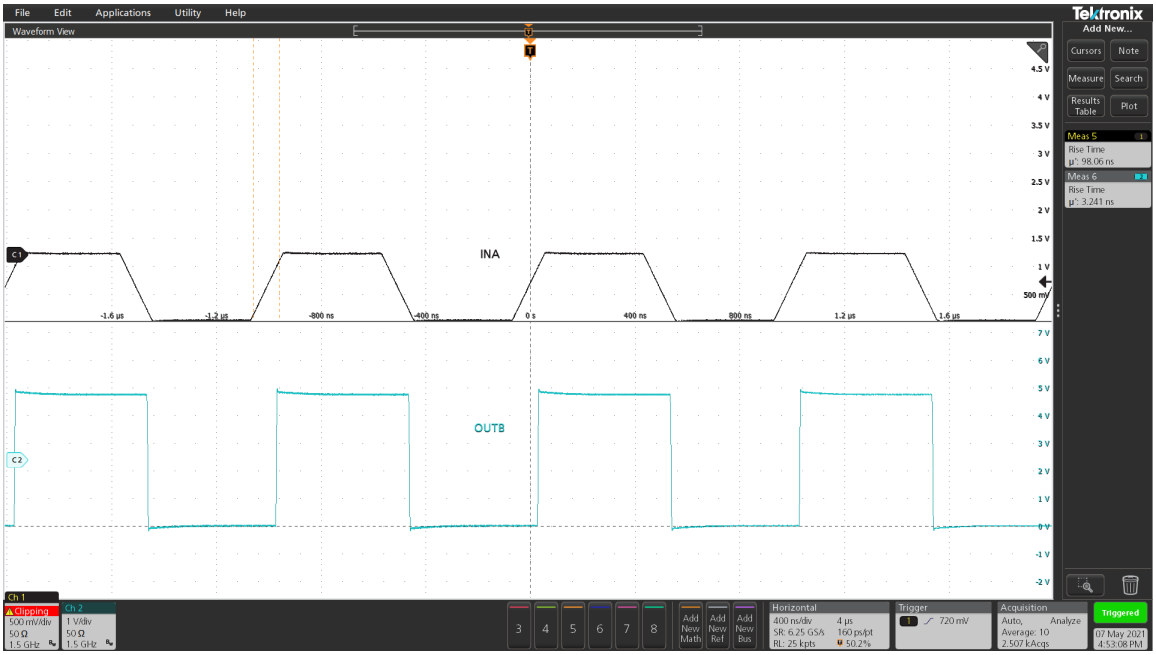


图 9-2. Up Translation at 1 MHz (1.2 V to 5 V)

10 Power Supply Recommendations

Always apply a ground reference to the GND pins first. This device is designed for glitch free power sequencing without any supply sequencing requirements such as ramp order or ramp rate.

Glitch-Free Power Supply Sequencing describes how this device was designed with various power supply sequencing methods in mind to help prevent unintended triggering of downstream devices.

11 Layout

11.1 Layout Guidelines

To ensure reliability of the device, following common printed-circuit board layout guidelines are recommended:

- Use bypass capacitors on the power supply pins and place them as close to the device as possible. A 0.1 µF capacitor is recommended, but transient performance can be improved by having 1 µF and 0.1 µF capacitors in parallel as bypass capacitors.
- The high drive capability of this device creates fast edges into light loads so routing and load conditions should be considered to prevent ringing.

11.2 Layout Example

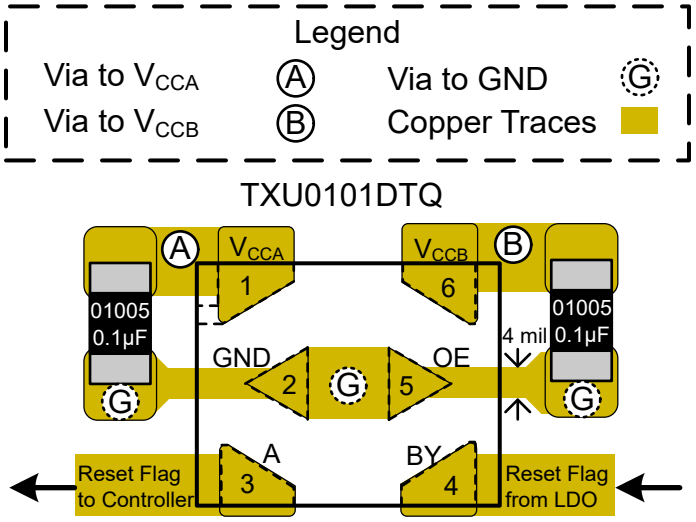


图 11-1. Layout Example – TXU0101

12 Device and Documentation Support

12.1 Device Support

12.1.1 Regulatory Requirements

No statutory or regulatory requirements apply to this device.

There are no special characteristics for this product.

12.2 Documentation Support

12.2.1 Related Documentation

- Texas Instruments, *Understanding Schmitt Triggers* application report
- Texas Instruments, *CMOS Power Consumption and C_{pd} Calculation* application report

12.3 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.4 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.5 Trademarks

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12.6 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.7 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TXU0101DBVR	ACTIVE	SOT-23	DBV	6	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	2T9H	Samples
TXU0101DCKR	ACTIVE	SC70	DCK	6	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	1LQ	Samples
TXU0101DRYR	ACTIVE	SON	DRY	6	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	MO	Samples
TXU0101DTQR	ACTIVE	X2SON	DTQ	6	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	MN	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals.
TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

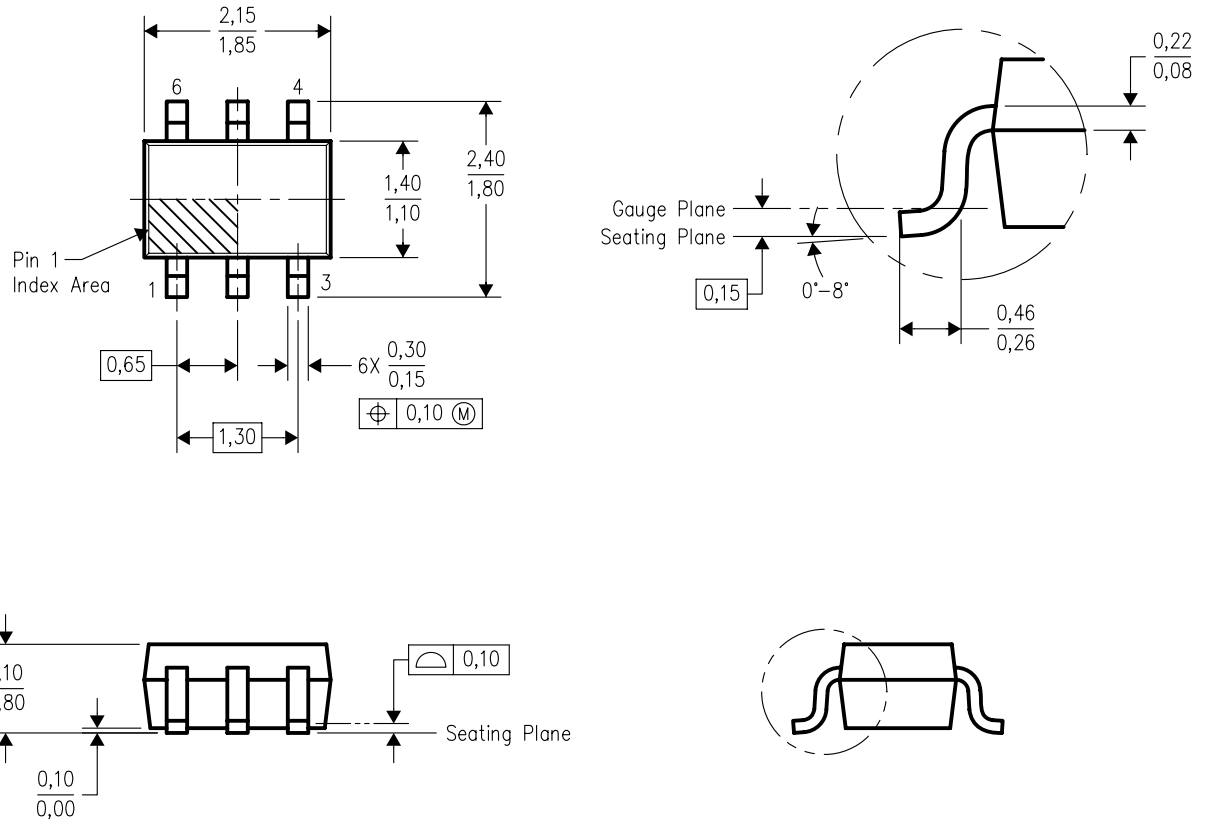
OTHER QUALIFIED VERSIONS OF TXU0101 :

- Automotive : TXU0101-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

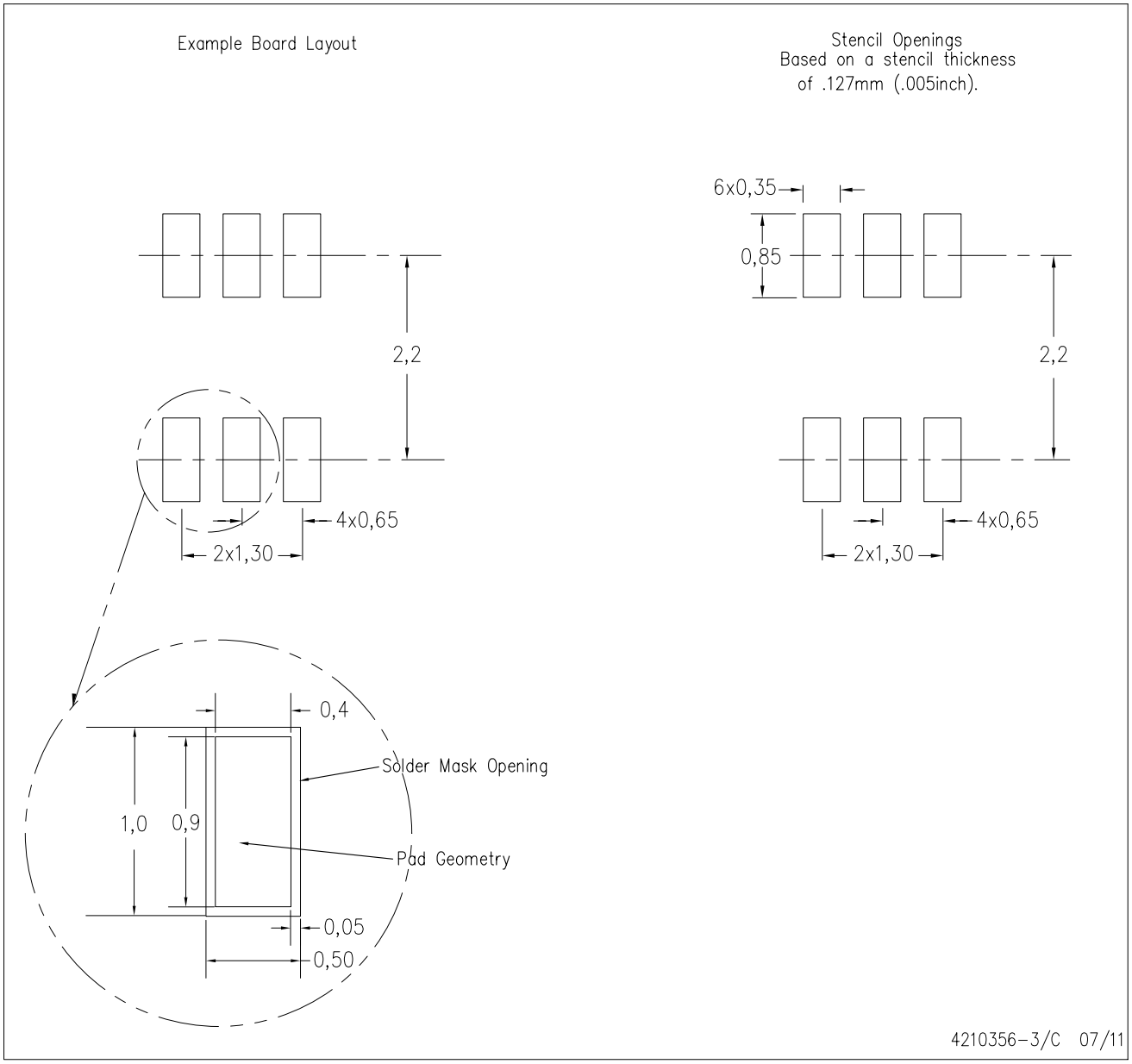
DCK (R–PDSO–G6) PLASTIC SMALL–OUTLINE PACKAGE



4093553–4/G 01/2007

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–203 variation AB.

DCK (R–PDSO–G6) PLASTIC SMALL OUTLINE



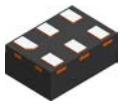
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.

DRY 6 USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

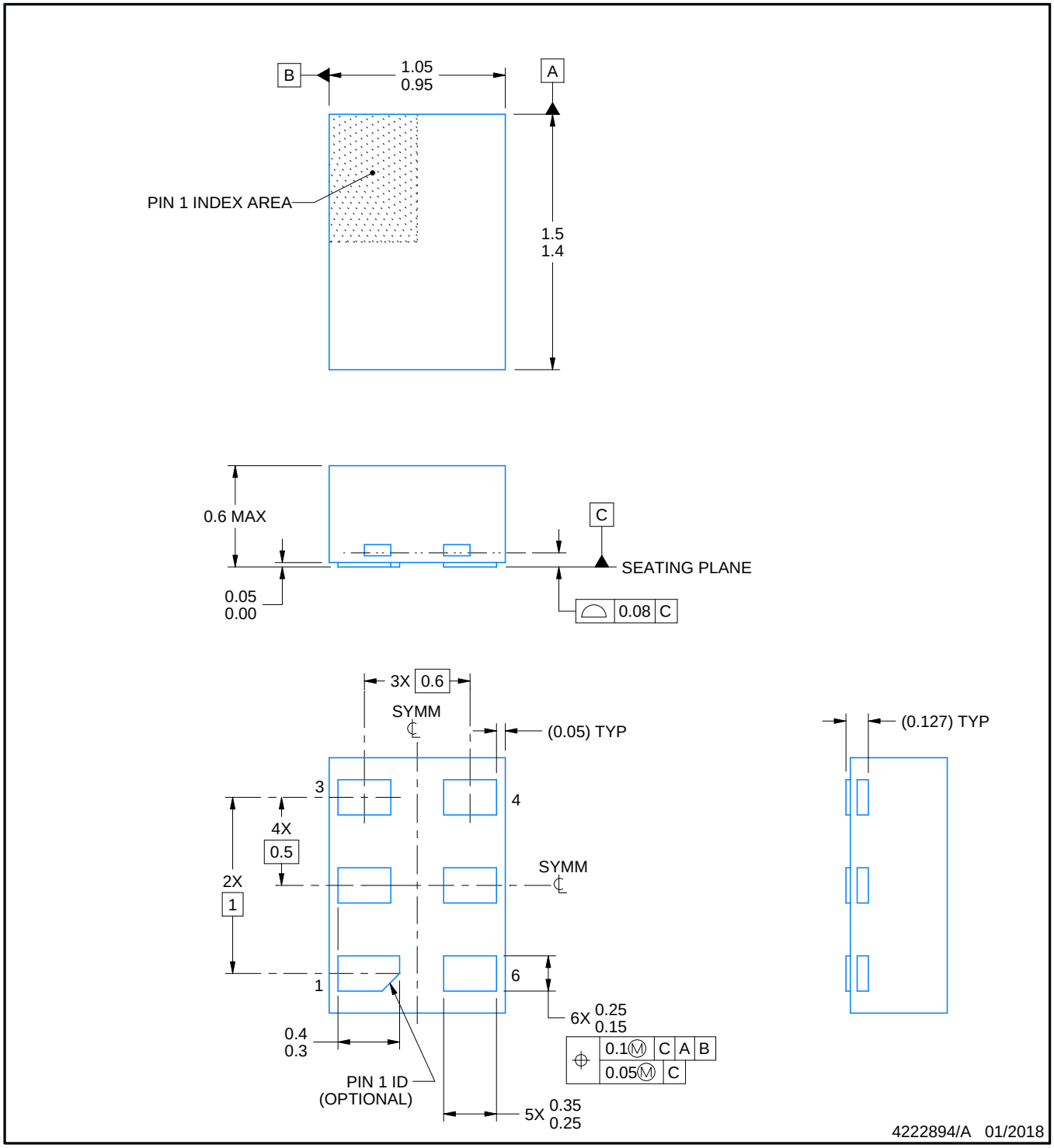
DRY0006A



PACKAGE OUTLINE

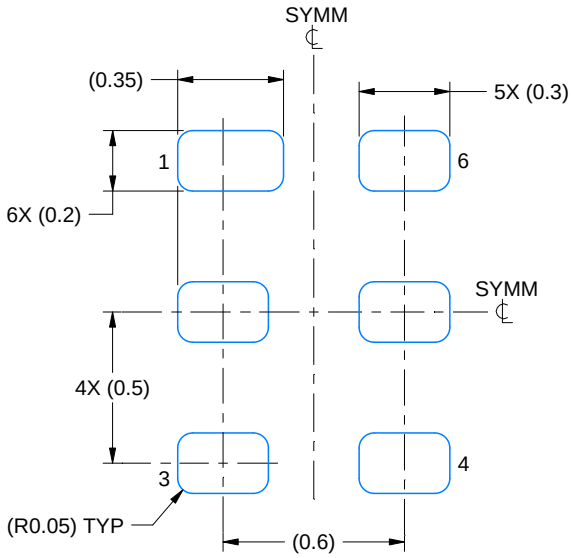
USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

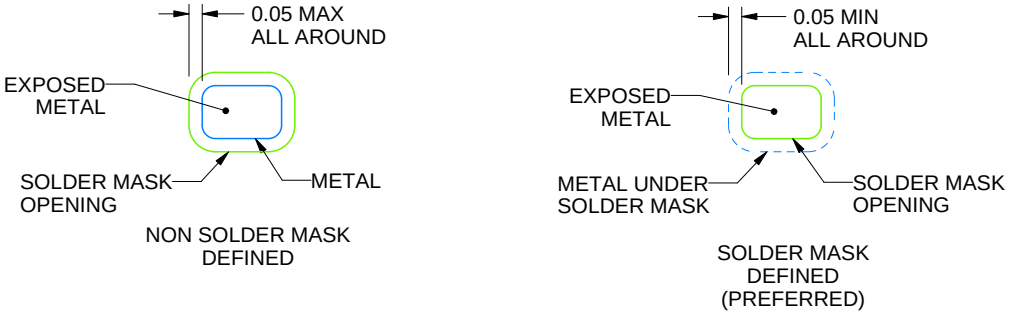


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
1:1 RATIO WITH PKG SOLDER PADS
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

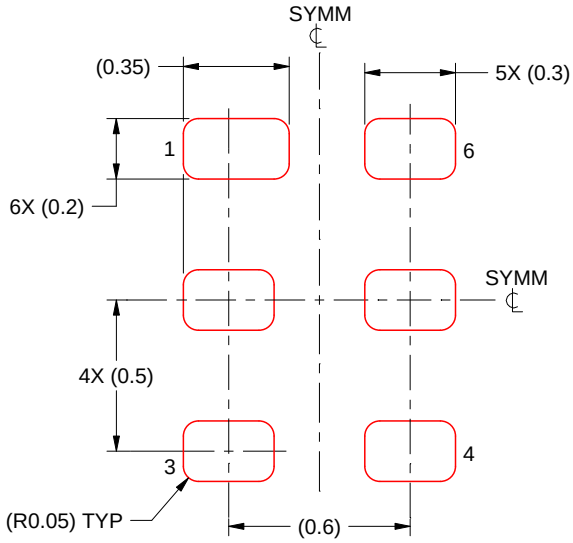
3. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.075 - 0.1 mm THICK STENCIL
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

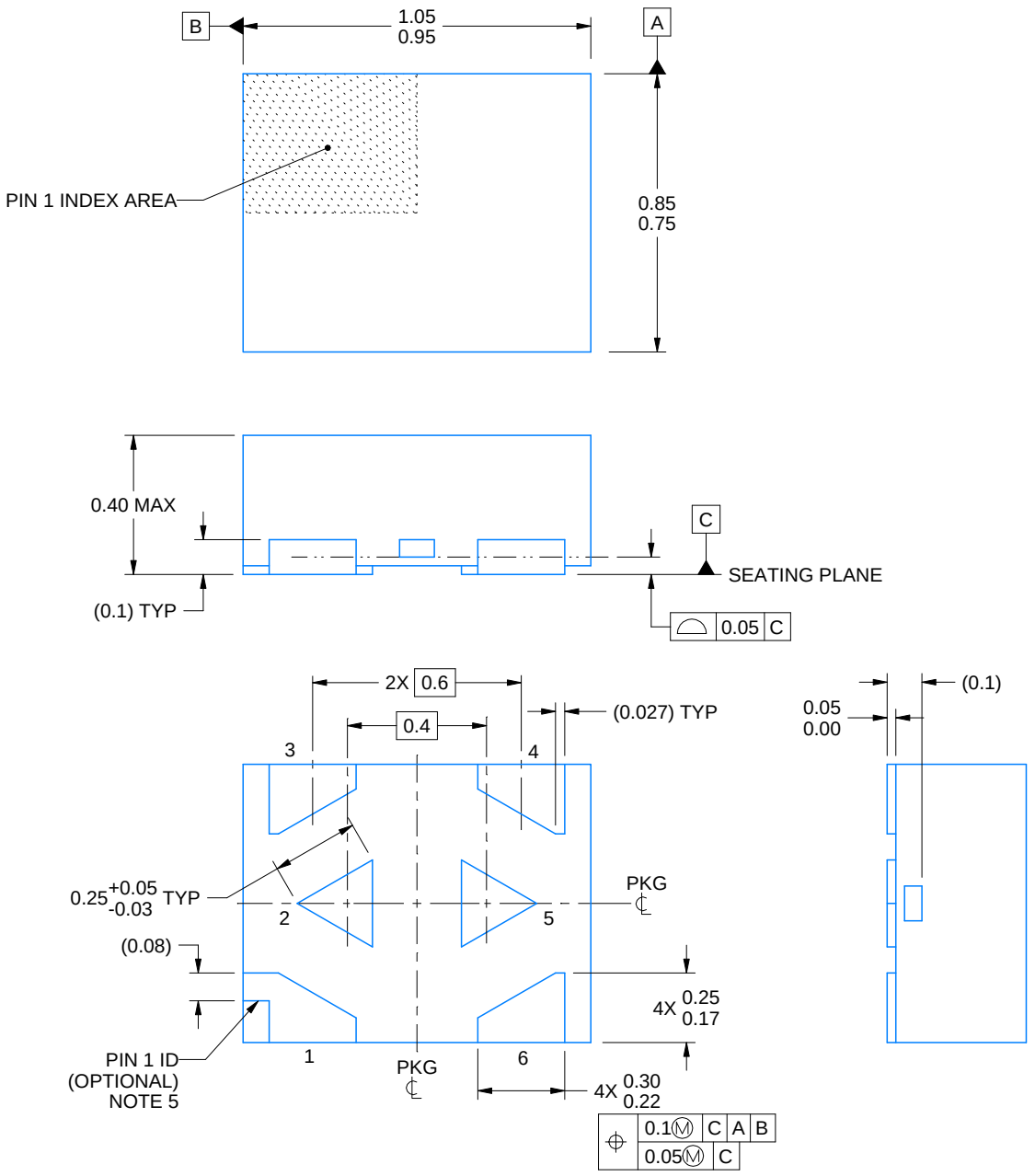
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

DTQ0006A

PACKAGE OUTLINE

X2SON - 0.4 mm max height

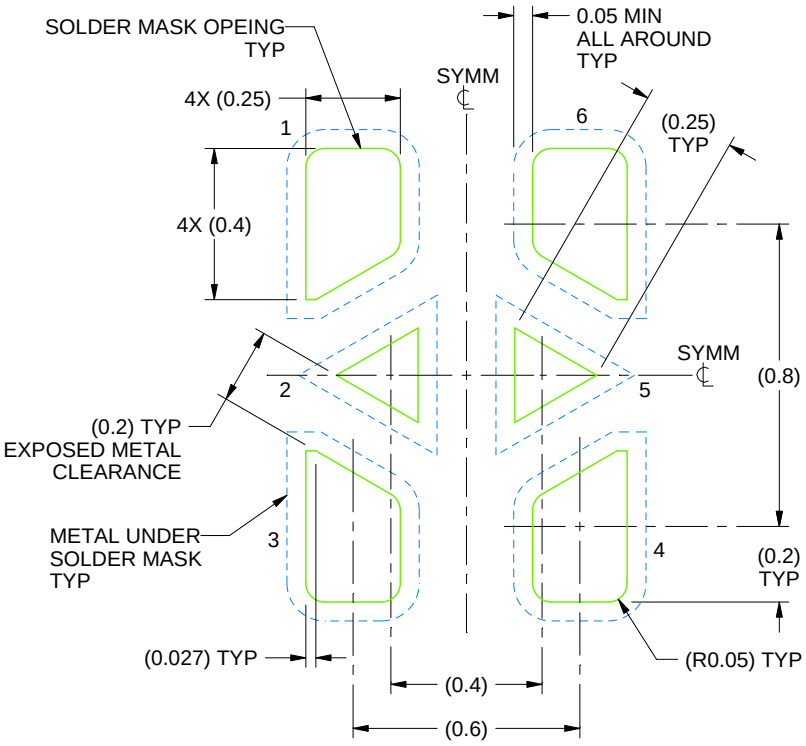
PLASTIC SMALL OUTLINE - NO LEAD



4224056/A 11/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.
4. The size and shape of this feature may vary.
5. Features may not exist. Recommend use of pin 1 marking on top of package for orientation purposes.

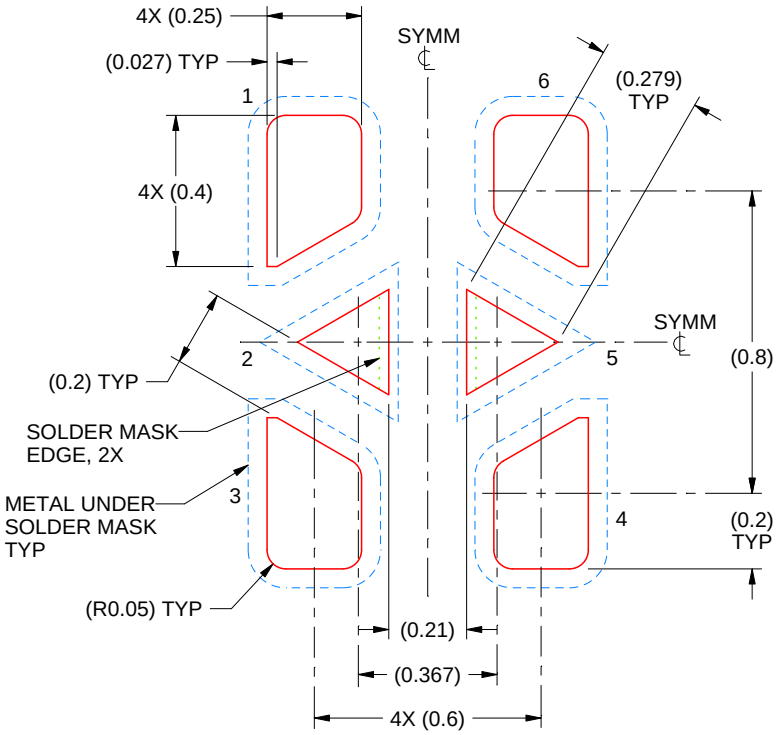


LAND PATTERN EXAMPLE
SOLDER MASK DEFINED
SCALE:50X

4224056/A 11/2017

NOTES: (continued)

6. This package is designed to be soldered to a thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
7. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.



SOLDER PASTE EXAMPLE
BASED ON 0.07 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:50X

4224056/A 11/2017

NOTES: (continued)

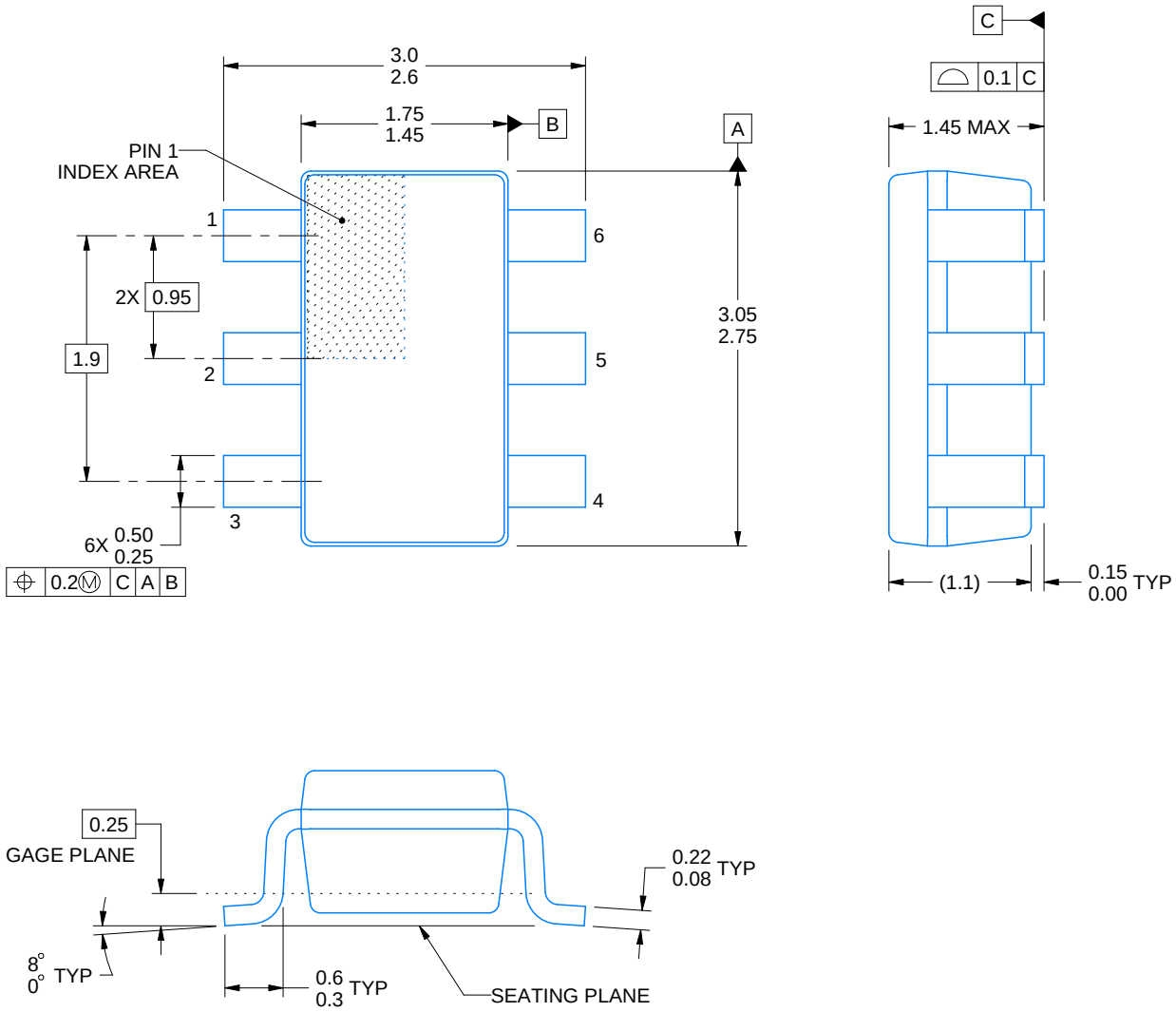
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGE OUTLINE

DBV0006A

SOT-23 - 1.45 mm max height

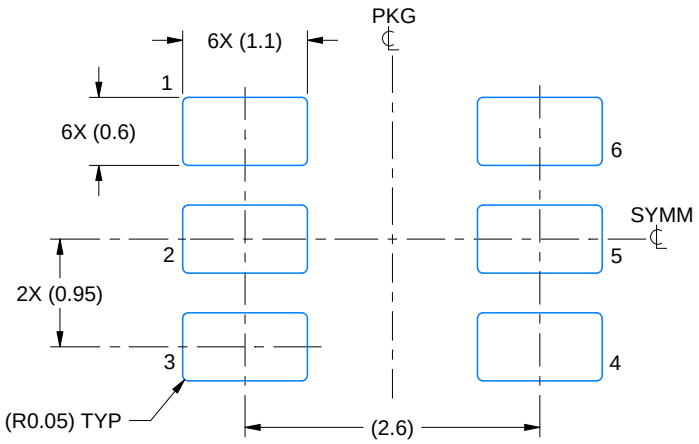
SMALL OUTLINE TRANSISTOR



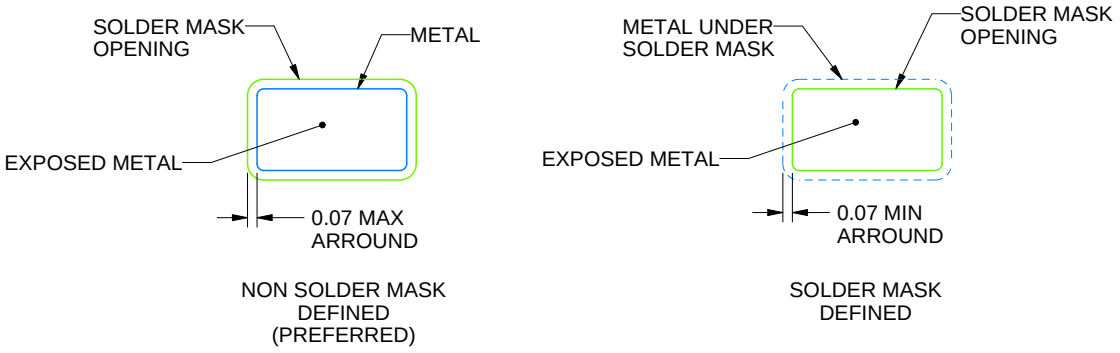
4214840/C 06/2021

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.
4. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
5. Refernce JEDEC MO-178.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

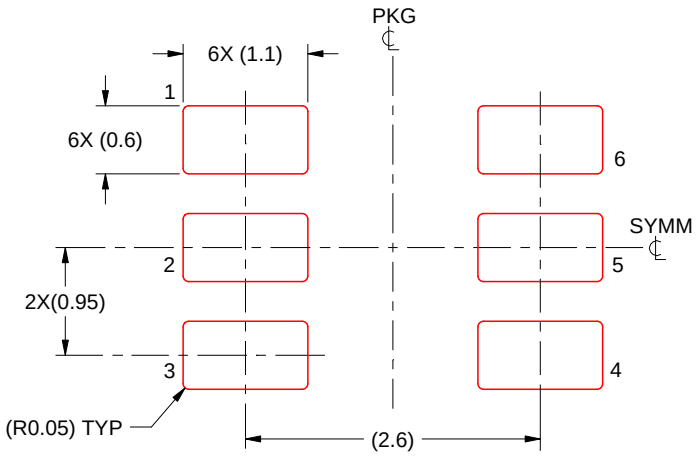


SOLDER MASK DETAILS

4214840/C 06/2021

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214840/C 06/2021

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

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